



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP060N06N		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000963520						
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2048.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.602	0.37	0.37	3711	3711
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		687	
	inorganic material	phosphorus	7723-14-0	0.422	0.02		206	
	non noble metal	copper	7440-50-8	1404.801	68.58	68.67	685873	686766
wire	non noble metal	aluminium	7429-90-5	3.208	0.16	0.16	1566	1566
encapsulation	organic material	carbon black	1333-86-4	8.864	0.43		4328	
	plastics	epoxy resin	-	97.499	4.76		47603	
	inorganic material	silicondioxide	60676-86-0	484.541	23.66	28.85	236570	288501
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10479	10479
plating	non noble metal	nickel	7440-02-0	0.244	0.01		119	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	119
solder	noble metal	silver	7440-22-4	0.454	0.02		221	
	non noble metal	tin	7440-31-5	0.363	0.02		177	
	non noble metal	lead	7439-92-1	17.327	0.85	0.89	8460	8858
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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